#### Femto pre-acceptance at Finetech December 3<sup>rd</sup> and 4<sup>th</sup>









#### The CMS Femto-machine was accepted

#### **ACCEPTANCE DETAILS**

- All standard parts function
  - Safety appliance, movement, rotation, accuracy, repeatability, force, heating, dispensing, imaging, pattern recognition etc.
- All standard parts within specs
  - In fact our machine fits the specs very well and is one of the most precise
     Femtos ever made (concerning position reproducibility and planarity)
- Special CMS parts work, but need small rework \(\square\)
  It was the first live test of:
  - the improved formic acid chamber design
  - o the new chip bond tool
    - new technology: first ever made (to our needs)
    - high force, fast heating AND self leveling







#### The CMS formic acid chamber receives minor rework until installation at DESY

FORMIC ACID CHAMBER ISSUES

The first handling during bonding tests with CMS dummy revealed some issues:

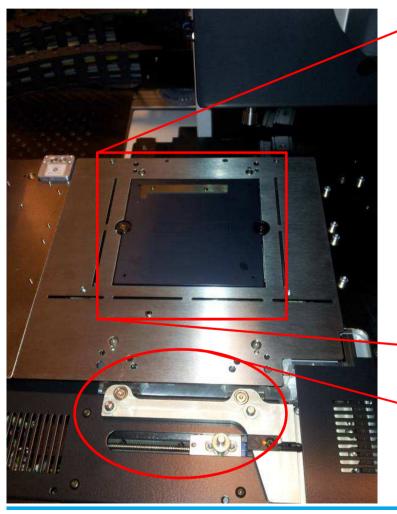
- Moveable chamber cover didn't move far enough to include the whole sensor area in its workspace
- Annoying software warnings occured when cover was to move to sensor corners for alignment procedure (limit of x and y movement)
- Handles missing on the chamber cover
- Alignment pins of the substrate handle transport cover stick with the substrate handle due to thermal expansion (100°C)

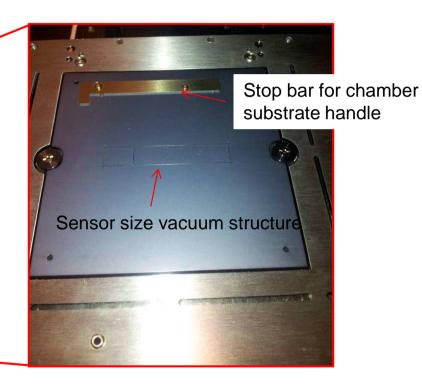






CMS FEMTO HEATING PLATE PICTURES





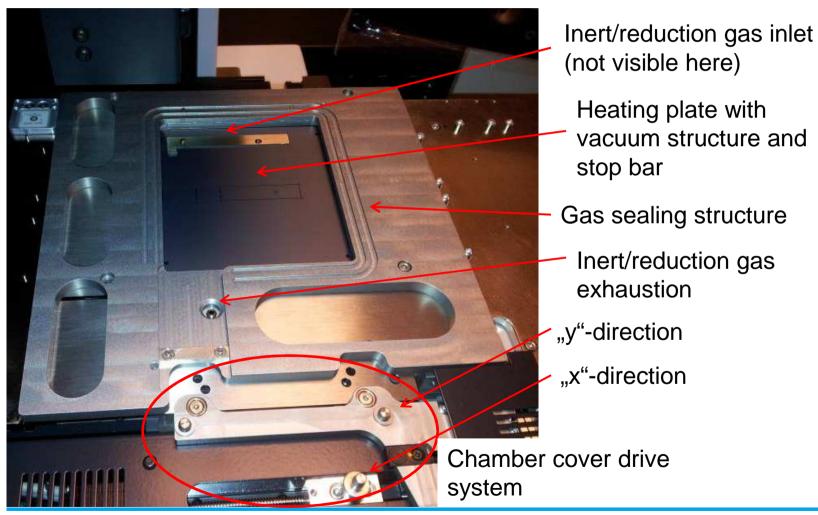
Chamber cover drive system







CMS FEMTO FORMIC ACID CHAMBER / PICTURE OF THE CHAMBER FRAME



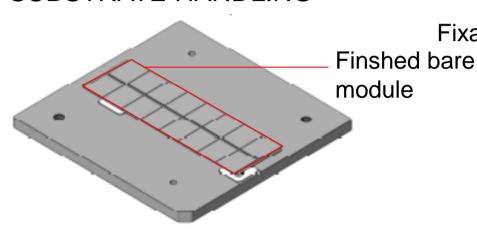






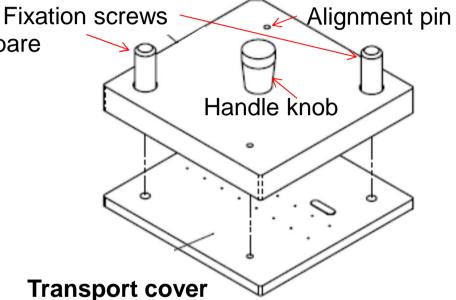
Jan Hampe

CMS FEMTO FORMIC ACID CHAMBER / SCHEMATICS OF THE SUBSTRATE HANDLING



#### Substrate handle inside process chamber

- Constructed to CMS sensor and ROC dimensions
- Vacuum hold below each chip area
- Also usable with single sensors



- Screwed to substrate handle
- For (de-)mounting the handle to/from the chamber
- Pocket allows for mounted bare module

Also flip cover made for module flipping and handling on probe station







CMS FEMTO FORMIC ACID CHAMBER / PICTURE OF THE CLOSED CHAMBER

- Cover is moved to position its opening above the current placeing position
- During reflow the chip bond tool is lowered to close the opening in the cover

